



generated by the same source that drives the data output, the relationship to the data is not significantly affected by voltage, temperature and process, as would be the case if the clock were generated by an outside source.

All interfaces of the DDR II SIO are HSTL, allowing speeds beyond SRAM devices that use any form of TTL interface. The interface can be scaled to higher voltages (up to 1.9V) to interface with 1.8V systems if necessary. The device has a VDDQ and a separate Vref, allowing the user to designate the interface operational voltage, independent of the device core voltage of 1.8V VDD. The output impedance control allows the user to adjust the drive strength to adapt to a wide range of loads and transmission lines.

Clocking

The DDRII SIO SRAM has two sets of input clocks, namely the K, $\bar{K}$ clocks and the C, $\bar{C}$ clocks. In addition, the DDRII SIO has an output "echo" clock, CQ, $\bar{CQ}$.

The K and $\bar{K}$ clocks are the primary device input clocks. The K clock is used to clock in the control signals ($\bar{LD}$, $R/\bar{W}$ and $\bar{BWx}$), the address, and the first word of the data burst during a write operation. The $\bar{K}$ clock is used to clock in the control signals ($\bar{BWx}$) and the second word of the data burst during a write operation. The K and $\bar{K}$ clocks are also used internally by the SRAM. In the event that the user disables the C and $\bar{C}$ clocks, the K and $\bar{K}$ clocks will also be used to clock the data out of the output register and generate the echo clocks.

The C and $\bar{C}$ clocks may be used to clock the data out of the output register during read operations and to generate the echo clocks. C and $\bar{C}$ must be presented to the SRAM within the timing tolerances. The output data from the DDRII SIO will be closely aligned to the C and $\bar{C}$ input, through the use of an internal DLL. When C is presented to the DDRII SIO SRAM, the DLL will have already internally clocked the data to arrive at the device output simultaneously with the arrival of the $\bar{C}$ clock. The C and second data item of the burst will also correspond.

Single Clock Mode

The DDRII SIO SRAM may be operated with a single clock pair. C and $\bar{C}$ may be disabled by tying both signals high, forcing the outputs and echo clocks to be controlled instead by the K and $\bar{K}$ clocks.

DLL Operation

The DLL in the output structure of the DDRII SIO SRAM can be used to closely align the incoming clocks C and $\bar{C}$ with the output of the data, generating very tight tolerances between the two. The user may disable the DLL by holding $\bar{Doff}$ low. With the DLL off, the C and $\bar{C}$ (or K and $\bar{K}$ if C and $\bar{C}$ are not used) will directly clock the output register of the SRAM. With the DLL off, there will be a propagation delay from the time the clock enters the device until the data appears at the output.

Echo Clock

The echo clocks, CQ and $\bar{CQ}$, are generated by the C and $\bar{C}$ clocks (or K, $\bar{K}$ if C, $\bar{C}$ are disabled). The rising edge of C generates the rising edge of CQ, and the falling edge of $\bar{CQ}$. The rising edge of $\bar{C}$ generates the rising edge of $\bar{CQ}$ and the falling edge of CQ. This scheme improves

the correlation of the rising and falling edges of the echo clock and will improve the duty cycle of the individual signals.

The echo clock is very closely aligned with the data, guaranteeing that the echo clock will remain closely correlated with the data, within the tolerances designated.

Read and Write Operations

DDRII SIO devices internally store the two words of the burst as a single wide word and the words will retain their burst order. There is no ability to address an individual word level in a burst, as is possible in the DDRII common I/O devices. The byte signal can be used to prevent writing to any individual bytes, or combined to prevent writing word(s) of the burst.

Read operations are initiated by holding Read/Write control input ($R/\bar{W}$) high, the load control input ($\bar{LD}$) low and presenting the read address to the address port during the rising edge of K, which will latch the address. The data will then be read and will appear at the device output at the designated time in correspondence with the C and $\bar{C}$ clocks.

Write operations are initiated by holding the Read/Write control input ($R/\bar{W}$) low, the load control input ($\bar{LD}$) low and presenting the write address to the address port during the rising edge of K, which will latch the address. On the following rising edge of K, the first word of the two word burst must be present on the data input bus DQ[x:0], along with the appropriate byte write ($\bar{BWx}$) inputs. On the following rising edge of $\bar{K}$, the second half of the data write burst will be accepted at the device input with the designated ($\bar{BWx}$) inputs.

Output Enables

The DDRII SIO SRAM automatically enables and disables the Q[x:0] outputs. When a valid read is in progress, and data is present at the output, the output will be enabled. If no valid data is present at the output (read not active), the output will be disabled (high impedance). The echo clocks will remain valid at all times and cannot be disabled or turned off. During power-up the Q outputs will come up in a high impedance state.

Programmable Impedance

An external resistor, RQ, must be connected between the ZQ pin on the SRAM and Vss to allow the SRAM to adjust its output drive impedance. The value of RQ must be 5X the value of the intended drive impedance of the SRAM. The allowable range of RQ to guarantee impedance matching with a tolerance of +/- 10% is between 175 ohms and 350 ohms, with VDDQ = 1.5V. The output impedance is adjusted every 1024 clock cycles to correct for drifts in supply voltage and temperature. If the user wishes to drive the output impedance of the SRAM to its lowest value, the ZQ pin may be tied to VDDQ.

Pin Definitions

Symbol	Pin Function	Description
D[X:0]	Input Synchronous	Data input signals, sampled on the rising edge of K and $\bar{K}$ clocks during valid write operations 1M x 18 -- D[17:0]
$\overline{BW}_0, \overline{BW}_1$	Input Synchronous	Byte Write Select 0, 1 are active LOW. Sampled on the rising edge of the K and again on the rising edge of $\bar{K}$ clocks during write operations. Used to select which byte is written into the device during the current portion of the write operations. Bytes not written remain unaltered. Both byte writes are sampled on the same edge as the data. Deselecting a Byte Write Select will cause the corresponding byte of data to be ignored and not written in to the device. 1M x 18 -- $\overline{BW}_0$ controls DQ[8:0] and $\overline{BW}_1$ controls DQ[17:9]
SA	Input Synchronous	Address Inputs. Addresses are sampled on the rising edge of K clock during active read or write operations.
Q[X:0]	Output Synchronous	Data Output signals. These pins drive out the requested data during a Read operation. Valid data is driven out on the rising edge of both the C and $\bar{C}$ clocks during Read operations or K and $\bar{K}$ when operating in single clock mode. When the Read port is deselected, Q[X:0] are automatically three-stated.
$\overline{LD}$	Input Synchronous	Load Control Logic. Sampled on the rising edge of K. If $\overline{LD}$ is low, a two word burst read or write operation will be initiated as designated by the R/ $\bar{W}$ input. If $\overline{LD}$ is high during the rising edge of K, operations in progress will complete, but new operations will not be initiated.
R/ $\bar{W}$	Input Synchronous	Read or Write Control Logic. If $\overline{LD}$ is low during the rising edge of K, the R/ $\bar{W}$ indicates whether a new operation should be a read or write. If R/ $\bar{W}$ is high, a read operation will be initiated, if R/ $\bar{W}$ is low, a write operation will be initiated. If the $\overline{LD}$ input is high during the rising edge of K, the R/ $\bar{W}$ input will be ignored.
C	Input Clock	Positive Output Clock Input. C is used in conjunction with $\bar{C}$ to clock out the Read data from the device. C and $\bar{C}$ can be used together to deskew the flight times of various devices on the board back to the controller. See application example for further details.
$\bar{C}$	Input Clock	Negative Output Clock Input. $\bar{C}$ is used in conjunction with C to clock out the Read data from the device. C and $\bar{C}$ can be used together to deskew the flight times of various devices on the board back to the controller. See application example for further details.
K	Input Clock	Positive Input Clock Input. The rising edge of K is used to capture synchronous inputs to the device and to drive out data through Q[X:0] when in single clock mode. All accesses are initiated on the rising edge of K.
$\bar{K}$	Input Clock	Negative Input Clock Input. $\bar{K}$ is used to capture synchronous inputs being presented to the device and to drive out data through Q[X:0] when in single clock mode.
CQ, $\bar{CQ}$	Output Clock	Synchronous Echo clock outputs. The rising edges of these outputs are tightly matched to the synchronous data outputs and can be used as a data valid indication. These signals are free running and do not stop when the output data is three stated.
ZQ	Input	Output Impedance Matching Input. This input is used to tune the device outputs to the system data bus impedance. Q[X:0] output impedance is set to $0.2 \times R_Q$, where R_Q is a resistor connected between ZQ and ground. Alternately, this pin can be connected directly to VDDQ, which enables the minimum impedance mode. This pin cannot be connected directly to GND or left unconnected.

6432 tbl 02a

Pin Definitions continued

Symbol	Pin Function	Description
$\overline{\text{Doff}}$	Input	DLL Turn Off. When low this input will turn off the DLL inside the device. The AC timings with the DLL turned off will be different from those listed in this data sheet. There will be an increased propagation delay from the incidence of C and $\overline{\text{C}}$ to Q, or K and $\overline{\text{K}}$ to Q as configured. The propagation delay is not a tested parameter, but will be similar to the propagation delay of other SRAM devices in this speed grade.
TDO	Output	TDO pin for JTAG.
TCK	Input	TCK pin for JTAG.
TDI	Input	TDI pin for JTAG. An internal resistor will pull TDI to VDD when the pin is unconnected.
TMS	Input	TMS pin for JTAG. An internal resistor will pull TMS to VDD when the pin is unconnected.
NC		No connects inside the package. Can be tied to any voltage level.
VREF	Input Reference	Reference Voltage input. Static input used to set the reference level for HSTL inputs and Outputs as well as AC measurement points.
VDD	Power Supply	Power supply inputs to the core of the device. Should be connected to a 1.8V power supply.
VSS	Ground	Ground for the device. Should be connected to ground of the system.
VDDQ	Power Supply	Power supply for the outputs of the device. Should be connected to a 1.5V power supply for HSTL or scaled to the desired output voltage.

6432 tbl 02b

Pin Configuration IDT71P79804 (1M x 18)

	1	2	3	4	5	6	7	8	9	10	11
A	$\overline{\text{CQ}}$	Vss/ SA ⁽²⁾	NC/ SA ⁽¹⁾	R/W	$\overline{\text{BW1}}$	$\overline{\text{K}}$	NC	$\overline{\text{LD}}$	SA	Vss/ SA ⁽²⁾	CQ
B	NC	Q9	D9	SA	NC	K	$\overline{\text{BW0}}$	SA	NC	NC	Q8
C	NC	NC	D10	Vss	SA	SA	SA	Vss	NC	Q7	D8
D	NC	D11	Q10	Vss	Vss	Vss	Vss	Vss	NC	NC	D7
E	NC	NC	Q11	VDDQ	Vss	Vss	Vss	VDDQ	NC	D6	Q6
F	NC	Q12	D12	VDDQ	VDD	Vss	VDD	VDDQ	NC	NC	Q5
G	NC	D13	Q13	VDDQ	VDD	Vss	VDD	VDDQ	NC	NC	D5
H	$\overline{\text{Doff}}$	VREF	VDDQ	VDDQ	VDD	Vss	VDD	VDDQ	VDDQ	VREF	ZQ
J	NC	NC	D14	VDDQ	VDD	Vss	VDD	VDDQ	NC	Q4	D4
K	NC	NC	Q14	VDDQ	VDD	Vss	VDD	VDDQ	NC	D3	Q3
L	NC	Q15	D15	VDDQ	Vss	Vss	Vss	VDDQ	NC	NC	Q2
M	NC	NC	D16	Vss	Vss	Vss	Vss	Vss	NC	Q1	D2
N	NC	D17	Q16	Vss	SA	SA	SA	Vss	NC	NC	D1
P	NC	NC	Q17	SA	SA	C	SA	SA	NC	D0	Q0
R	TDO	TCK	SA	SA	SA	$\overline{\text{C}}$	SA	SA	SA	TMS	TDI

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165-ball FBGA Pinout Top View

NOTES:

1. A3 is reserved for the 36Mb expansion address.
2. A10 is reserved for the 72Mb expansion address. This must be tied or driven to VSS on the 1M x 18 DDRII SIO Burst of 2 (71P79804) devices.
3. A2 is reserved for the 144Mb expansion address. This must be tied or driven to VSS on the 1M x 18 DDRII SIO Burst of 2 (71P79804) devices.

Absolute Maximum Ratings^{(1) (2)}

Symbol	Rating	Value	Unit
V _{TERM}	Supply Voltage on V _{DD} with Respect to GND	-0.5 to +2.9	V
V _{TERM}	Supply Voltage on V _{DDQ} with Respect to GND	-0.5 to V _{DDQ} +0.3	V
V _{TERM}	Voltage on Input terminals with respect to GND	-0.5 to V _{DD} +0.3	V
V _{TERM}	Voltage on output and I/O terminals with respect to GND	-0.5 to V _{DDQ} +0.3	
T _{BIAS}	Temperature Under Bias	-55 to +125	°C
T _{STG}	Storage Temperature	-65 to +150	°C
I _{OUT}	Continuous Current into Outputs	± 20	mA

6432 tbl 05

Notes:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- V_{DDQ} must not exceed V_{DD} during normal operation.

Write Descriptions^(1,2)

Signal	BW ₀	BW ₁
Write Byte 0	L	X
Write Byte 1	X	L

6432 tbl 09

Notes:

- All byte write (BW_x) and () signals are sampled on the rising edge of K and again on $\bar{K}$. The data that is present on the data bus in the designated byte/ will be latched into the input if the corresponding BW_x or is held low. The rising edge of K will sample the first byte/ of the two word burst and the rising edge of $\bar{K}$ will sample the second byte of the two word burst.
- The availability of the BW_x or on designated devices is described in the pin description table.
- The DDR II SIO Burst of two SRAM has data forwarding. A read request that is initiated on cycle following a write request to the same address will produce the newly written data in response to the read request.

Capacitance (TA = +25°C, f = 1.0MHz)⁽¹⁾

Symbol	Parameter	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{DD} = 1.8V V _{DDQ} = 1.5V	5	pF
C _{CLK}	Clock Input Capacitance		6	pF
C _O	Output Capacitance		7	pF

6432 tbl 06

Note:

- Tested at characterization and retested after any design or process change that may affect these parameters.

Recommended DC Operating Conditions

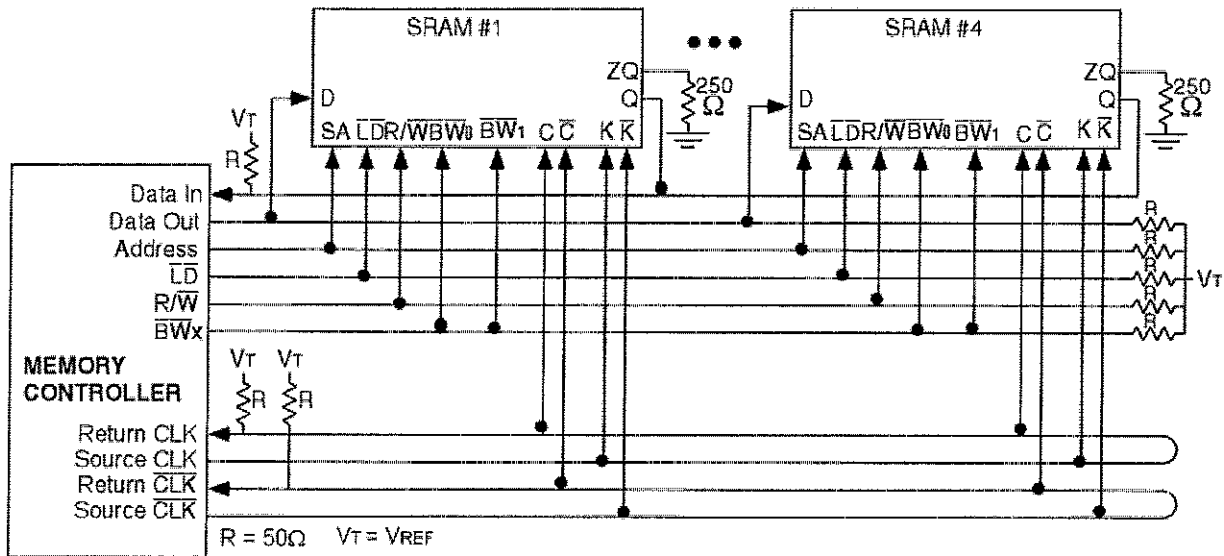
Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{DD}	Power Supply Voltage	1.7	1.8	1.9	V
V _{DDQ}	I/O Supply Voltage	1.4	1.5	1.9	V
V _{SS}	Ground	0	0	0	V
V _{REF}	Input Reference Voltage	-	V _{DDQ} /2	-	V
T _A	Ambient Temperature ⁽¹⁾	Commercial	0 to +70		°C
		Industrial	-40 to +85		°C

6432 tbl 04

Note:

- During production testing, the case temperature equals the ambient temperature.

Application Example



6432 dsw 20

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range ($V_{DD} = 1.8 \pm 100\text{mV}$, $V_{DDQ} = 1.4\text{V to } 1.9\text{V}$)

Parameter	Symbol	Test Conditions	Min	Max	Unit	Note		
Input Leakage Current	IIL	VDD = Max VIN = VSS to VDDQ	-2	+2	uA			
Output Leakage Current	IOL	Output Disabled	-2	+2	uA			
				Com'l	Ind			
Operating Current (x18): DDR	IDD	VDD = Max, IOUT = 0mA (outputs open), Cycle Time ≥ 1KHKH Min	267MHz	-	950	980	mA	1
			250MHz	-	850	900		
			200MHz	-	750	800		
			167MHz	-	650	700		
Standby Current: NOP	ISB1	Device Deselected (in NOP state) IOUT = 0mA (outputs open), f=Max, All Inputs ≤0.2V or ≥ VDD -0.2V	267MHz	-	420	450	mA	2
			250MHz	-	375	410		
			200MHz	-	335	370		
			167MHz	-	300	335		
Output High Voltage	VOH1	RQ = 250Ω, IOH = -15mA	VDDQ/2-0.12	VDDQ/2+0.12	V	3,7		
Output Low Voltage	VOL1	RQ = 250Ω, IOL = 15mA	VDDQ/2-0.12	VDDQ/2+0.12	V	4,7		
Output High Voltage	VOH2	IOH = -0.1mA	VDDQ-0.2	VDDQ	V	5		
Output Low Voltage	VOL2	IOL = 0.1mA	VSS	0.2	V	6		

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NOTES:

- Operating Current is calculated with 50% read cycles and 50% write cycles
- Standby Current is only after all pending read and write burst operations are completed.
- Outputs are impedance-controlled. $I_{OH} = -(V_{DDQ}/2)/(R_Q/5)$ and is guaranteed by device characterization for $175\Omega \leq R_Q < 350\Omega$. This parameter is tested at $R_Q = 250\Omega$, which gives a nominal 50Ω output impedance.
- Outputs are impedance-controlled. $I_{OL} = (V_{DDQ}/2)/(R_Q/5)$ and is guaranteed by device characterization for $175\Omega \leq R_Q < 350\Omega$. This parameter is tested at $R_Q = 250\Omega$, which gives a nominal 50Ω output impedance.
- This measurement is taken to ensure that the output has the capability of pulling to the V_{DDQ} rail, and is not intended to be used as an impedance measurement point.
- This measurement is taken to ensure that the output has the capability of pulling to V_{SS} , and is not intended to be used as an impedance measurement point.
- Programmable Impedance Mode

Input Electrical Characteristics Over the Operating Temperature and Supply Voltage Range ($V_{DD} = 1.8 \pm 100\text{mV}$, $V_{DDQ} = 1.4\text{V to } 1.9\text{V}$)

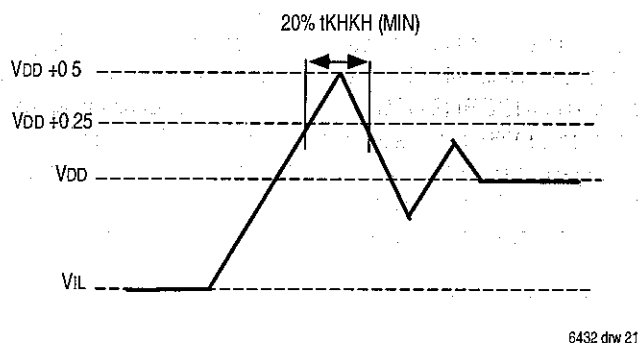
Parameter	Symbol	Min	Max	Unit	Notes
Input High Voltage, DC	$V_{IH}(\text{DC})$	$V_{REF} + 0.1$	$V_{DDQ} + 0.3$	V	1,2
Input Low Voltage, DC	$V_{IL}(\text{DC})$	-0.3	$V_{REF} - 0.1$	V	1,3
Input High Voltage, AC	$V_{IH}(\text{AC})$	$V_{REF} + 0.2$	-	V	4,5
Input Low Voltage, AC	$V_{IL}(\text{AC})$	-	$V_{REF} - 0.2$	V	4,5

NOTES:

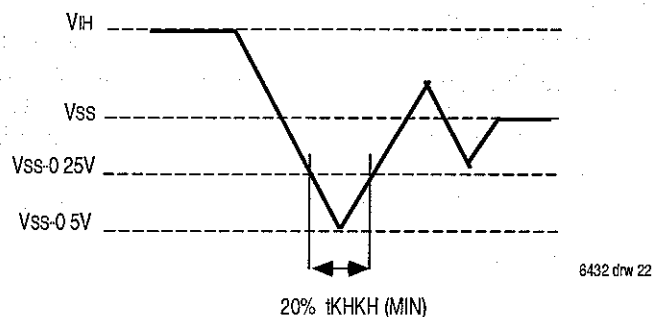
6432 tbl 10d

- These are DC test criteria. DC design criteria is $V_{REF} \pm 50\text{mV}$. The AC V_{IH}/V_{IL} levels are defined separately for measuring timing parameters.
- $V_{IH}(\text{Max}) \text{ DC} = V_{DDQ} + 0.3$, $V_{IH}(\text{Max}) \text{ AC} = V_{DD} + 0.5\text{V}$ (pulse width $\leq 20\% t_{KHKH}(\text{min})$)
- $V_{IL}(\text{Min}) \text{ DC} = -0.3\text{V}$, $V_{IL}(\text{Min}) \text{ AC} = -0.5\text{V}$ (pulse width $\leq 20\% t_{KHKH}(\text{min})$)
- This condition is for AC function test only, not for AC parameter test.
- To maintain a valid level, the transitioning edge of the input must:
 - Sustain a constant slew rate from the current AC level through the target AC level, $V_{IL}(\text{AC})$ or $V_{IH}(\text{AC})$
 - Reach at least the target AC level.
 - After the AC target level is reached, continue to maintain at least the target DC level, $V_{IL}(\text{DC})$ or $V_{IH}(\text{DC})$

Overshoot Timing



Undershoot Timing



AC Test Conditions

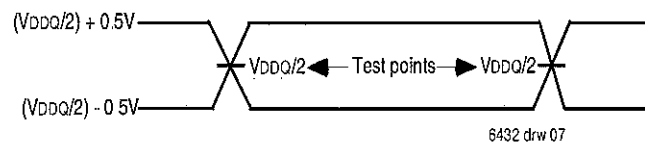
Parameter	Symbol	Value	Unit
Core Power Supply Voltage	VDD	1.7-1.9	V
Output Power Supply Voltage	VDDQ	1.4-1.9	V
Input High Level	V _{IH}	(VDDQ/2) + 0.5	V
Input Low Level	V _{IL}	(VDDQ/2) - 0.5	V
Input Reference Level	VREF	VDDQ/2	V
Input Rise/Fall Time	TR/TF	0.3/0.3	ns
Output Timing Reference Level		VDDQ/2	V

NOTE:

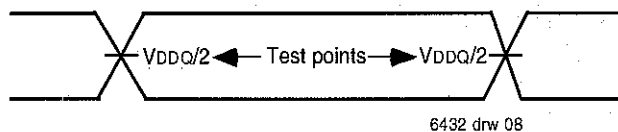
1 Parameters are tested with RQ=250Ω

6432 tbl 11a

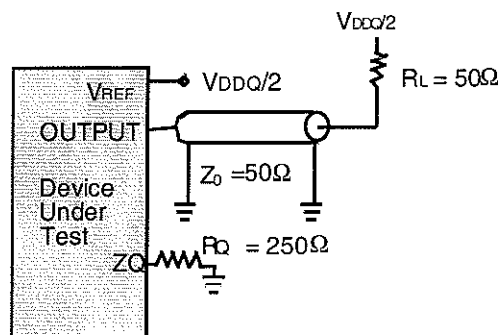
Input Waveform



Output Waveform



AC Test Loads



AC Electrical Characteristics

(VDD = 1.8 ± 100mV, VDDQ = 1.4V to 1.9V, Commercial and Industrial Temperature Ranges)^(3,7)

Symbol	Parameter	267MHz		250MHz		200MHz		167MHz		Unit	Notes
		Min.	Max	Min	Max	Min.	Max	Min.	Max		
Clock Parameters											
tKHKH	Clock Cycle Time (K, $\overline{K}$,C,C)	3.75	6.30	4.00	6.30	5.00	7.88	6.00	8.40	ns	
tKC var	Clock Phase Jitter (K, $\overline{K}$,C,C)	-	-	-	0.20	-	0.20	-	0.20	ns	1,5
tKHKL	Clock High Time (K, $\overline{K}$,C,C)	1.50	-	1.60	-	2.00	-	2.40	-	ns	8
tKLKH	Clock LOW Time (K, $\overline{K}$,C,C)	1.50	-	1.60	-	2.00	-	2.40	-	ns	8
tKH $\overline{K}$ H	Clock to $\overline{\text{clock}}$ (K $\rightarrow$ $\overline{K}$,C $\rightarrow$ $\overline{C}$)	1.69	-	1.80	-	2.20	-	2.70	-	ns	9
t $\overline{K}$ HKH	$\overline{\text{Clock}}$ to clock ($\overline{K}$ $\rightarrow$ K, $\overline{C}$ $\rightarrow$ C)	1.69	-	1.80	-	2.20	-	2.70	-	ns	9
tKHCH	Clock to data clock (K $\rightarrow$ C, $\overline{K}$ $\rightarrow$ $\overline{C}$)	0.00	1.69	0.00	1.80	0.00	2.30	0.00	2.80	ns	
tKC lock	DLL lock time (K, C)	1024	-	1024	-	1024	-	1024	-	cycles	2
tKC reset	K static to DLL reset	30	-	30	-	30	-	30	-	ns	
Output Parameters											
tCHQV	C, $\overline{C}$ HIGH to output valid	-	0.45	-	0.45	-	0.45	-	0.50	ns	3
tCHQX	C, $\overline{C}$ HIGH to output hold	-0.45	-	-0.45	-	-0.45	-	-0.50	-	ns	3
tCHCQV	C, $\overline{C}$ HIGH to echo clock valid	-	0.45	-	0.45	-	0.45	-	0.50	ns	3
tCHCQX	C, $\overline{C}$ HIGH to echo clock hold	-0.45	-	-0.45	-	-0.45	-	-0.50	-	ns	3
tCQHQV	CQ, $\overline{CQ}$ HIGH to output valid	-	0.30	-	0.30	-	0.35	-	0.40	ns	
tCQHQX	CQ, $\overline{CQ}$ HIGH to output hold	-0.30	-	-0.30	-	-0.35	-	-0.40	-	ns	
tCHQZ	C HIGH to output High-Z	-	0.45	-	0.45	-	0.45	-	0.50	ns	3,4,5
tCHQX1	C HIGH to output Low-Z	-0.45	-	-0.45	-	-0.45	-	-0.50	-	ns	3,4,5
Set-Up Times											
tAVKH	Address valid to K, $\overline{K}$ rising edge	0.50	-	0.50	-	0.60	-	0.70	-	ns	6
tIVKH	R/ $\overline{W}$ inputs valid to K, $\overline{K}$ rising edge	0.50	-	0.50	-	0.60	-	0.70	-	ns	
tDVKH	Data-in and $\overline{BW}$ x valid to K, $\overline{K}$ rising edge	0.35	-	0.35	-	0.40	-	0.50	-	ns	
Hold Times											
tKHAX	K, $\overline{K}$ rising edge to address hold	0.50	-	0.50	-	0.60	-	0.70	-	ns	6
tKHIX	K, $\overline{K}$ rising edge to R/ $\overline{W}$ inputs hold	0.50	-	0.50	-	0.60	-	0.70	-	ns	
tKHDX	K, $\overline{K}$ rising edge to data-in and $\overline{BW}$ x hold	0.35	-	0.35	-	0.40	-	0.50	-	ns	

NOTES:

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- 1 Clock phase jitter is the variance from clock rising edge to the next expected clock rising edge.
- 2 Vdd slew rate must be less than 0.1V DC per 50 ns for DLL lock retention. DLL lock time begins once Vdd and input clock are stable.
- 3 If C, $\bar{C}$ are tied High, K, $\bar{K}$ become the references for C, $\bar{C}$ timing parameters.
- 4 To avoid bus contention, at a given voltage and temperature tCHQX1 is bigger than tCHQZ. The specs as shown do not imply bus contention because tCHQX1 is a MIN parameter that is worse case at totally different test conditions (0°C, 1.9V) than tCHQZ, which is a MAX parameter (worst case at 70°C, 1.7V) It is not possible for two SRAMs on the same board to be at such different voltage and temperature.
- 5 This parameter is guaranteed by device characterization, but not production tested.
- 6 All address inputs must meet the specified setup and hold times for all latching clock edges.
- 7 During production testing, the case temperature equals TA.
- 8 Clock High Time (tKHKL) and Clock Low Time (tKLKH) should be within 40% to 60% of the cycle time (tKHKH).
- 9 Clock to clock time (tKH $\bar{K}$ H) and $\bar{\text{Clock}}$ to clock time (t $\bar{K}$ HKH) should be within 45% to 55% of the cycle time (tKHKH).

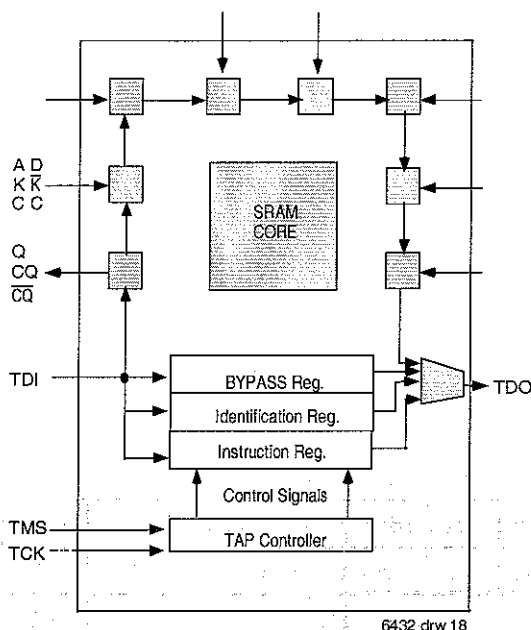
[illegible]

IEEE 1149.1 TEST ACCESS PORT AND BOUNDARY SCAN-JTAG

This part contains an IEEE standard 1149.1 Compatible Test Access Port (TAP). The package pads are monitored by the Serial Scan circuitry when in test mode. This is to support connectivity testing during manufacturing and system diagnostics. In conformance with IEEE 1149.1, the SRAM contains a TAP controller, Instruction register, Bypass Register and ID register. The TAP controller has a standard 16-state machine that resets internally upon power-up; therefore, the TRST signal is not

required. It is possible to use this device without utilizing the TAP. To disable the TAP controller without interfacing with normal operation of the SRAM, TCK must be tied to VSS to preclude a mid level input. TMS and TDI are designed so an undriven input will produce a response identical to the application of a logic 1, and may be left unconnected, but they may also be tied to VDD through a resistor. TDO should be left unconnected

JTAG Block Diagram



JTAG Instruction Coding

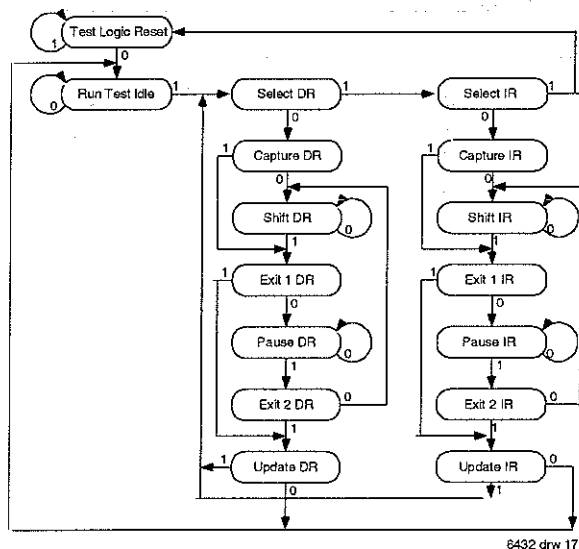
IR2	IR1	IR0	Instruction	TDO Output	Notes
0	0	0	EXTEST	Boundary Scan Register	
0	0	1	IDCODE	Identification register	2
0	1	0	SAMPLE-Z	Boundary Scan Register	1
0	1	1	RESERVED	Do Not Use	5
1	0	0	SAMPLE/PRELOAD	Boundary Scan register	4
1	0	1	RESERVED	Do Not Use	5
1	1	0	RESERVED	Do Not Use	5
1	1	1	BYPASS	Bypass Register	3

NOTES:

6432 tbl 13

1. Places Qs in Hi-Z in order to sample all input data regardless of other SRAM inputs
2. TDI is sampled as an input to the first ID register to allow for the serial shift of the external TDI data.
3. Bypass register is initialized to Vss when BYPASS instruction is invoked. The Bypass Register also holds serially loaded TDI when exiting the Shift DR states.
4. SAMPLE instruction does not place output pins in Hi-Z.
5. This instruction is reserved for future use

TAP Controller State Diagram



Scan Register Definition

Part	Instruction Register	Bypass Register	ID Register	Boundry Scan
1Mx18	3 bits	1 bit	32 bits	107 bits

6432 tbl 14

Identification Register Definitions

INSTRUCTION FIELD	ALL DEVICES	DESCRIPTION	PART NUMBER
Revision Number (31:29)	0x0	Revision Number	
Device ID (28:12)	0x0299	1Mx18 DDRII SIO BURST OF 2	71P79804S
IDT JEDEC ID CODE (11:1)	0x033	Allows unique identification of SRAM vendor.	
ID Register Presence Indicator (0)	1	Indicates the presence of an ID register.	

6432 tbl 15

Boundary Scan Exit Order

ORDER	PIN ID
1	6R
2	6P
3	6N
4	7P
5	7N
6	7R
7	8R
8	8P
9	9R
10	11P
11	10P
12	10N
13	9P
14	10M
15	11N
16	9M
17	9N
18	11L
19	11M
20	9L
21	10L
22	11K
23	10K
24	9J
25	9K
26	10J
27	11J
28	11H
29	10G
30	9G
31	11F
32	11G
33	9F
34	10F
35	11E
36	10E

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ORDER	PIN ID
37	10D
38	9E
39	10C
40	11D
41	9C
42	9D
43	11B
44	11C
45	9B
46	10B
47	11A
48	Internal
49	9A
50	8B
51	7C
52	6C
53	8A
54	7A
55	7B
56	6B
57	6A
58	5B
59	5A
60	4A
61	5C
62	4B
63	3A
64	1H
65	1A
66	2B
67	3B
68	1C
69	1B
70	3D
71	3C
72	1D

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ORDER	PIN ID
73	2C
74	3E
75	2D
76	2E
77	1E
78	2F
79	3F
80	1G
81	1F
82	3G
83	2G
84	1J
85	2J
86	3K
87	3J
88	2K
89	1K
90	2L
91	3L
92	1M
93	1L
94	3N
95	3M
96	1N
97	2M
98	3P
99	2N
100	2P
101	1P
102	3R
103	4R
104	4P
105	5P
106	5N
107	5R

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JTAG DC Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit	Note
Output Power Supply	VDDQ	1.4	-	1.9	V	
Power Supply Voltage	VDD	1.7	1.8	1.9	V	
Input High Level	V _{IH}	1.3	-	VDD + 0.3	V	
Input Low Level	V _{IL}	- 0.3	-	0.5	V	
TCK Input Leakage Current	I _{IL}	- 5	-	+ 5	uA	
TMS, TDI Input Leakage Current	I _{IL}	- 15	-	+ 15	uA	
TDO Output Leakage Current	I _{OL}	- 5	-	+ 5	uA	
Output High Voltage (I _{OH} = -1mA)	V _{OH}	VDDQ - 0.2	-	VDDQ	V	1
Output Low Voltage (I _{OL} = 1mA)	V _{OL}	VSS	-	0.2	V	1

6432 tbl 19

NOTE:

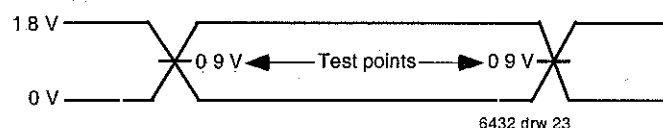
- The output impedance of TDO is set to 50 ohms (nominal process) and does not vary with the external resistor connected to ZQ.

JTAG AC Test Conditions

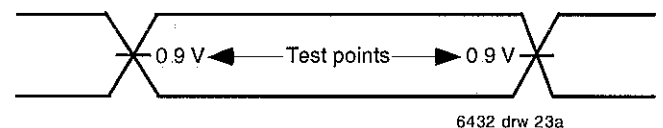
Parameter	Symbol	Min	Unit	Note
Input High Level	V _{IH}	1.8	V	
Input Low Level	V _{IL}	0	V	
Input Rise/Fall Time	T _R /T _F	1.0/1.0	ns	
Input and Output Timing Reference Level		0.9	V	1

Note: 1. For SRAM outputs see AC test output load on page 13

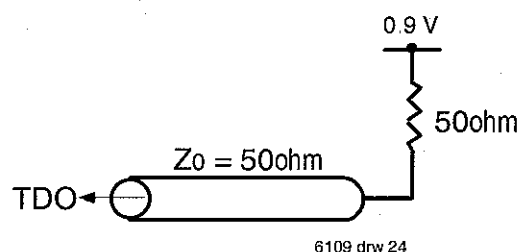
JTAG Input Test WaveForm



JTAG Output Test WaveForm



JTAG AC Test Load

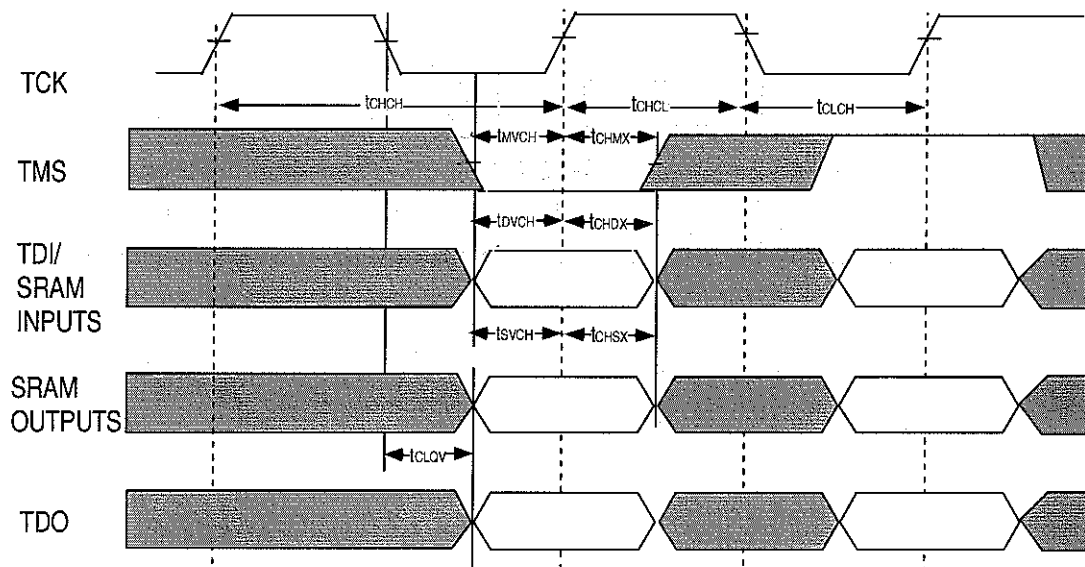


JTAG AC Characteristics

Parameter	Symbol	Min	Max	Unit	Note
TCK Cycle Time	tCHCH	50	-	ns	
TCK High Pulse Width	tCHCL	20	-	ns	
TCK Low Pulse Width	tCLCH	20	-	ns	
TMS Input Setup Time	tMVCH	5	-	ns	
TMS Input Hold Time	tCHMX	5	-	ns	
TDI Input Setup Time	tDVCH	5	-	ns	
TDI Input Hold Time	tCHDX	5	-	ns	
SRAM Input Setup Time	tSVCH	5	-	ns	
SRAM Input Hold Time	tCHSX	5	-	ns	
Clock Low to Output Valid	tCLOV	0	10	ns	

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JTAG Timing Diagram



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REVISIONS			
DCN	REV	DESCRIPTION	DATE APPROVE
00		INITIAL RELEASE	05/01/00

(165 BALL SHOWN)

TELEPHONE UNLESS SPECIFIED DECIMAL INCHES FRACTIONS		Integrated Device Technology, Inc. 2915 Shuman Way, Santa Clara, CA 95050 Phone: (408) 257-1010 Fax: (408) 422-8274 TBE 910-138-001	
APPROVALS	DATE	TITLE	REV
DRAWN BY	05/01/00	BGA PACKAGE OUTLINE	00
CHECKED		13.0 X 15.0 mm BODY	
		FPBGA	
		SIZE DRAWING NO.	
		PSC-4086	
		DO NOT SCALE DRAWING	SHEET 1 OF

REVISIONS			
DCN	REV	DESCRIPTION	DATE APPROVE
00		INITIAL RELEASE	05/01/00

(165 BALL)

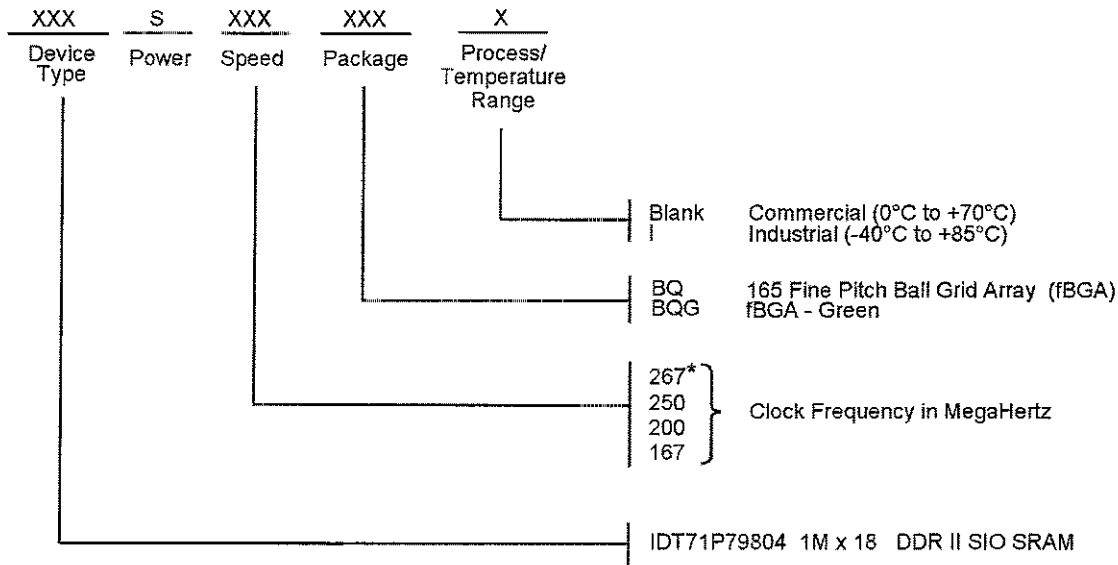
NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994
- 2 "a" REPRESENTS THE BASIC SOLDER BALL GRID PITCH
- 3 "m" REPRESENTS THE MAXIMUM SOLDER BALL MATRIX SIZE
- 4 "n" REPRESENTS THE BALLCOUNT NUMBER
- △ DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM [C]
- △ SEATING PLANE AND PRIMARY DATUM [C] ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS
- △ "A1" ID CORNER MUST BE IDENTIFIED BY CHAMFER, INK MARK, METALLIZED MARKING, INDENTATION OR OTHER FEATURE ON PACKAGE BODY
- △ IF "A1" ID CORNER IS ON PACKAGE BODY IT MUST BE LOCATED WITHIN THE ZONE INDICATED
- 9 ALL DIMENSIONS ARE IN MILLIMETERS

SYMBOL	JEDEC VARIATION			NOTE
	NOT YET REGISTERED			
	MIN	NOM	MAX	
A	-	-	1.20	
A1	.30	.35	.40	
A2	.78	.85	.92	
D	15.00 BSC			
E	13.00 BSC			
M	11 X 15			3
N	165			4
e	1.00 BSC			
b	.35	.45	.50	5
CENTER BALL MARK	N/A			

TOLERANCES UNLESS SPECIFIED DIMENAL INCHES FRACTIONS		Integrated Device Technology, Inc. 2915 Shuman Way, Santa Clara, CA 95050 Phone: (408) 257-1010 Fax: (408) 422-8274 TBE 910-138-001	
APPROVALS	DATE	TITLE	REV
DRAWN BY	05/01/00	BGA PACKAGE OUTLINE	00
CHECKED		13.0 X 15.0 mm BODY	
		FPBGA	
		SIZE DRAWING NO.	
		PSC-4086	
		DO NOT SCALE DRAWING	SHEET 2 OF

Ordering Information



6432 drw15



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 QDR SRAMs and Quad Data Rate RAMs comprise a new family of products developed by Cypress Semiconductor, IDT, and Micron Technology, Inc.

Revision History

<u>REV</u>	<u>DATE</u>	<u>PAGES</u>	<u>DESCRIPTION</u>
0	07/26/05	p 1-21	Released Final datasheet
1	11/30/05	p. 11,14,22	Added 267MHz speed grade to the DC and AC Electrical Characteristics tables and ordering information
2	11/01/08	p 1-22	Deleted 71P79204/104/604 devices from datasheet. Updated the ordering information by removing the "IDT" notation.